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TITLE: Wet etching of thermally or chemically cured polyimide

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In addition, when etching the chemically cured polyimides, partially etched polyimide often remains, forming what has been referred to as "spider webs".

It has been found, in accordance with the present invention, that such partially etched polyimide can be removed without forming new partially etched

polyimide by contacting with an inorganic acid such as hydrochloric acid or sulfuric acid. When chromium is also present, the acid employed is sulfuric acid since hydrochloric acid will attack the chromium. The acids generally have a concentration of about 20% volume to about 70% volume, typical being 22%

volume to about 25% volume.